

13th IEEE International Conference on High Performance Computing (HiPC 2006)

Bangalore, India, December 18-21, 2006

Sponsorship Information

The IEEE International Conference on High Performance Computing (HiPC) is the leading conference in India addressing the broad area of high performance computing and communication. The conference emphasizes the design and analysis of high performance parallel, distributed, networked and mobile sensor-based systems, and their scientific, engineering, and commercial applications. HiPC 2006, the 13th conference in this series, will be held in Bangalore, India during December 18-21, 2006. Further information about the conference can be found at www.hipc.org.

I. Platinum Level, INR 500,000 (US\$12000)

- 25 minute technical presentation as part of the conference **Industry Keynote Track***
- 10 complementary conference registrations
- Literature distributed with the conference registration kit
- Large-size logo on conference website and publicity materials**
- Large booth at the conference exhibition

II. Gold Level, INR 300,000 (US\$7000)

- 10 complementary conference registrations
- Literature distributed with the conference registration kit
- Logo on conference website and publicity materials**
- Large booth at the conference exhibition

III. Silver Level, INR 100,000 (US\$2500)

- 3 complementary conference registrations
- Literature distributed with the conference registration kit
- Logo on conference website and in publicity materials**

Additional sponsor opportunities (Please contact HiPC Industry Co-chairs for details):

- Student best paper awards
- Student travel awards
- Conference banquet and cultural event
- Poster session and reception
- Registration kit

For more information please contact the **HiPC 2006 Industry Co-Chairs:**

Vijay Mann, IBM India Research Lab, India

Email: vijamann@in.ibm.com

Raghuram Tupuri, Advanced Micro Devices (AMD), India

Email: raghuram.tupuri@amd.com

^{*} Only six presentation slots are available.

^{**} Logos will be placed on the conference website and on the banner in the conference hall.